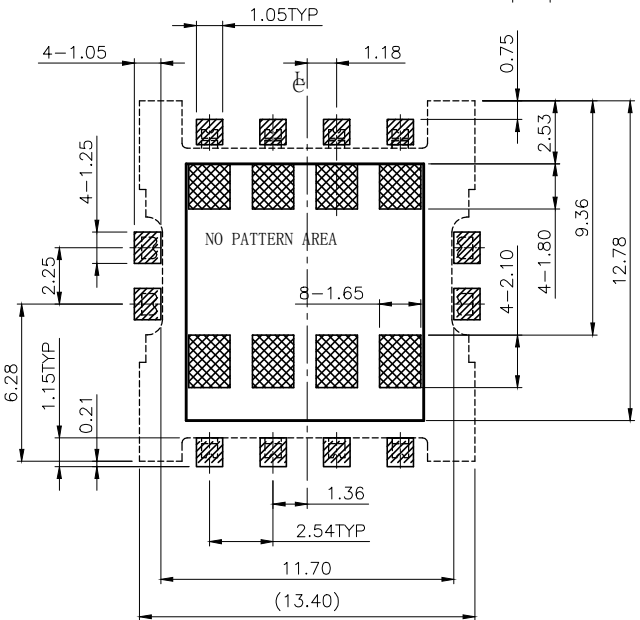
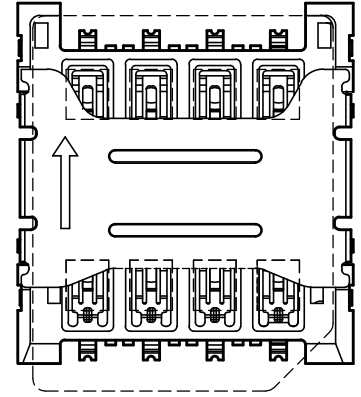
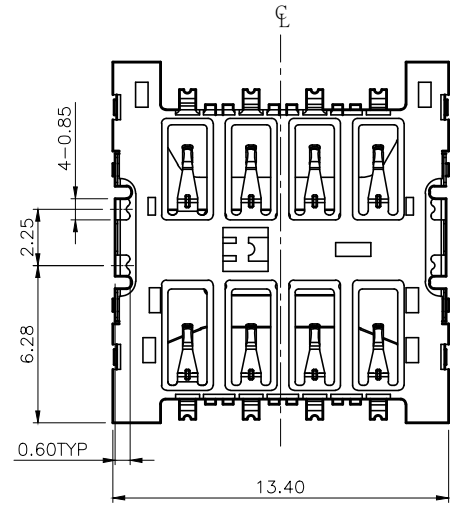
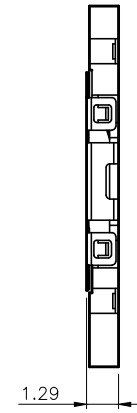
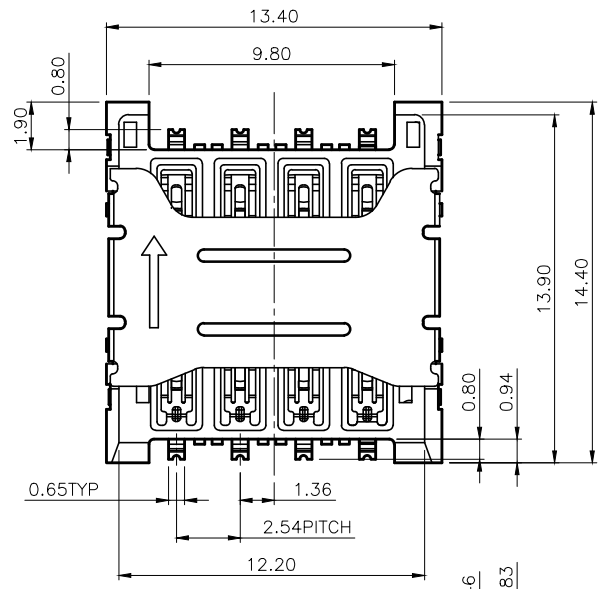
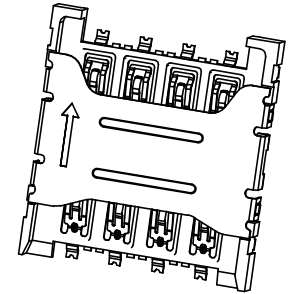


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31



RECOMMENDED P.C.B. LAYOUT TOLERANCE: ±0.05 TOP VIEW

- PCB AREA
- CONNECT AREA
- KEEP OUT AREA



MATERIALS

1. HOUSING : THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY,
PLATING : GOLD PLATED ON CONTACT AREA AND SOLDER TAILS,NICKEL PLATED OVERALL.
3. SHELL : STAINLESS STEEL.
PLATING : NICKEL PLATED OVERALL.
GOLD PLATED ON SOLDER TAILS

SPECIFICATION

1. CURRENT RATING : 1.0 A MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE : 500V AC R.M.S. FOR ONE MINUTE.
3. INSULATION RESISTANCE : 100M次MIN. AT 500V DC.
4. CONTACT RESISTANCE : 30m次MAX.
5. OPERATING TEMPERATURE : -40°C TO +85°C.

DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

GENERAL TOLERANCE		DWG NO.	JYSA0422-001	APPD:	WIND	Scale	1:1
X±0.45	x:±5'	Title	MICRO SIM SOCKET 8PIN 1.30H (焊接脚内折防浪PIN)	CHKD:		UNIT	mm
.X±0.35	.x'±2'	Part NO.	JYS-SIM130-111	DR:			
.XX±0.25	.xx'±1'	Date	2012/02/29				
.XXX±0.15	.xxx'±0.5'	杰宇森电子有限公司 JIE YU SEN ELECTRONIC CO.,LTD.					
SHEET	1/1						